

L8 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2008 ACS on STN  
 AN 2000:181103 CAPLUS  
 DN 132:223592  
 ED Entered STN: 21 Mar 2000  
 TI Polyamide compositions for bonding of electronic parts at high  
 temperature, and solvent- and heat-bonding methods using the compositions  
 IN Nakanishi, Takashi; Sugiyama, Masahide  
 PA Tomoegawa Paper Co., Ltd., Japan  
 SO Jpn. Kokai Tokkyo Koho, 10 pp.  
 CODEN: JKXXAF  
 DT Patent  
 LA Japanese  
 IC ICM C09J177-06  
 ICS C08L077-06; H01B003-30; H01F005-06  
 CC 38-3 (Plastics Fabrication and Uses)  
 Section cross-reference(s): 76

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2000080344	A	20000321	JP 1998-267322	19980904 <--
	JP 3523082	B2	20040426		
PRAI	JP 1998-267322		19980904		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
JP 2000080344	ICM	C09J177-06
	ICS	C08L077-06; H01B003-30; H01F005-06
	IPCI	C09J0177-06 [ICM,7]; C08L0077-06 [ICS,7]; H01B0003-30 [ICS,7]; H01F0005-06 [ICS,7]
	IPCR	H01F0005-06 [I,C*]; H01F0005-06 [I,A]; C08L0077-00 [I,C*]; C08L0077-06 [I,A]; C09J0177-00 [I,C*]; C09J0177-06 [I,A]; H01B0003-30 [I,C*]; H01B0003-30 [I,A]

AB The compns. contain phenolic OH-containing aromatic polyamides and linear polyamides having methoxymethylated amide groups. A solution containing 50 parts

alc.-soluble 5-hydroxyisophthalic acid-Kayabond C 300 [bis(4-amino-3,5-diethylphenyl)methane] copolymer (intrinsic viscosity 0.60 dL/g at 30°) and 50 parts FR-101 (30% methoxymethylated linear polyamide) was applied on 2 sheets of Cu foil and they were adhered by heat-bonding or solvent-bonding method to show both 80% adhesive strength retention at 180° compared with adhesive strength at 25°.

ST heat resistance adhesive methoxymethylated polyamide electronic; solvent heat bonding electronic part polyamide; phenolic hydroxy polyamide adhesive heat resistance; hydroxyisophthalic acid aminodiethylphenylmethane copolymer adhesive electronic

IT Polyamides, uses

RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(aromatic; heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT Adhesion, physical

Electric apparatus

Electric conductors

(heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT Adhesives

(heat-resistant; heat-resistant polyamide compns. for solvent- and

heat-bonding of elec. parts)

IT Polyamides, uses  
 RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)  
 (linear, methoxymethylated; heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT Alcohols, uses  
 RL: NUU (Other use, unclassified); USES (Uses)  
 (solvents; heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT 7440-50-8, Copper, miscellaneous  
 RL: MSC (Miscellaneous)  
 (foil; heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT 146187-38-4P, 3,4'-Diaminodiphenyl ether-5-hydroxyisophthalic acid copolymer 146584-70-5P, 3,4'-Diaminodiphenyl ether-5-hydroxyisophthalic acid copolymer, sru 180579-38-8P, 5-Hydroxyisophthalic acid-Kayabond C 300 copolymer 180579-39-9P, 5-Hydroxyisophthalic acid-Kayabond C 300 copolymer, sru 180579-40-2P, 5-Hydroxyisophthalic acid-Kayabond C 300-isophthalic acid copolymer 180579-41-3P, Curehard MED-5-hydroxyisophthalic acid copolymer 180579-45-7P 223132-36-3P, 5-Hydroxyisophthalic acid-Kayabond C 400 copolymer 232585-23-8P  
 RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)  
 (heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT 25035-02-3, Fine Resin FR 104 112353-50-1, Fine Resin FR 101 261621-50-5, Fine Resin FR 105  
 RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)  
 (heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

IT 64-17-5, Ethanol, uses  
 RL: NUU (Other use, unclassified); USES (Uses)  
 (solvent; heat-resistant polyamide compns. for solvent- and heat-bonding of elec. parts)

RN 7440-50-8  
 RN 146187-38-4P  
 RN 146584-70-5P  
 RN 180579-38-8P  
 RN 180579-39-9P  
 RN 180579-40-2P  
 RN 180579-41-3P  
 RN 180579-45-7P  
 RN 223132-36-3P  
 RN 232585-23-8P  
 RN 25035-02-3  
 RN 112353-50-1  
 RN 261621-50-5  
 RN 64-17-5

L8 ANSWER 2 OF 3 WPIX COPYRIGHT 2008 THOMSON REUTERS on STN  
 AN 2000-286909 [25] WPIX  
 DNC C2000-087034 [25]  
 DNN N2000-216118 [25]  
 TI Resin composition for adhesion of electronic device - comprises aromatic polyamide with at least phenolic hydroxyl, and linear polyamide resin  
 DC A23; A85; G03; L03; V02; V04; X12  
 IN NAKANISHI T; SUGIYAMA H  
 PA (TOMO-C) TOMOEGAWA SEISHISHO KK

CYC 1

PI JP 2000080344 A 20000321 (200025)\* JA 10[0] <--  
JP 3523082 B2 20040426 (200428) JA 10

ADT JP 2000080344 A JP 1998-267322 19980904; JP 3523082 B2 JP  
1998-267322 19980904

FDT JP 3523082 B2 Previous Publ JP 2000080344 A

PRAI JP 1998-267322 19980904

IPCR C08L0077-00 [I,C]; C08L0077-06 [I,A]; C09J0177-00 [I,C]; C09J0177-06  
[I,A]; H01B0003-30 [I,A]; H01B0003-30 [I,C]; H01F0005-06 [I,A];  
H01F0005-06 [I,C]

AB JP 2000080344 A UPAB: 20060116  
NOVELTY - Resin composition comprises aromatic polyamide with at least  
phenolic hydroxyl, and linear polyamide resin in which a part of amide is  
methoxymethylated.  
DETAILED DESCRIPTION - Resin composition comprises aromatic polyamide with  
at least phenolic hydroxyl and linear polyamide resin in which a part of  
amide is methoxymethylated.  
An INDEPENDENT CLAIM is also included for method of adhesion using the  
resin composition comprising applying and drying the resin composition to  
the surface of an adherend, forming resin film on the surface of the  
adherend, heating the film and putting another adherend to the surface of  
the film.  
USE - The resin composition is useful for adhesion of electronic  
devices, preferably for insulating a wire used for coils.  
ADVANTAGE - The resin composition exhibits improved adhesiveness and  
insulating capacity and less lowers the adhesive property at higher  
temperature.

MC CPI: A05-F01E2; A12-E02A; A12-E07C; G03-B02E; L03-A01B3; L03-B02F;  
L04-C17D  
EPI: V02-G02B1; V04-X01B; X12-C01B; X12-E02B

L8 ANSWER 3 OF 3 JAPIO (C) 2008 JPO on STN

AN 2000-080344 JAPIO

TI RESIN COMPOSITION AND BONDING METHOD USING THE SAME

IN NAKANISHI TAKAYUKI; SUGIYAMA HITOHIDE

PA TOMOEGAWA PAPER CO LTD

PI JP 2000080344 A 20000321 Heisei

AI JP 1998-267322 (JP10267322 Heisei) 19980904

PRAI JP 1998-267322 19980904

SO PATENT ABSTRACTS OF JAPAN (CD-ROM), Unexamined Applications, Vol. 2000

IC ICM C09J177-06  
ICS C08L077-06; H01B003-30; H01F005-06

AB PROBLEM TO BE SOLVED: To improve heat resistance, insulating properties  
and adhesiveness at a high temperature of a resin composition by blending  
an aromatic polyamide resin having a phenolic hydroxide group and a  
specific linear polyamide resin.  
SOLUTION: An aromatic polyamide resin having a phenolic hydroxide group  
which resin comprises 5-100 mol% of a repeating unit of formula I and 0-95  
mol% of a repeating unit of formula II is obtained by reacting an aromatic  
diamine compound having at least one alkyl group on the ortho-position of  
the terminal amino aryl group and an aromatic dicarboxylic acid having a  
phenolic hydroxide group. 1-70 pts.weight of the aromatic polyamide resin is  
blended with an alcohol-soluble linear polyamide resin whose amide groups  
are partially di-methylated in the amount such that the total be 100  
pts.weight In the formulas, Ar is a bivalent aromatic group, R and R' are  
each H or a 1-4C alkyl but both are not H simultaneously, R2 is a 1-3C  
alkylene which may be substituted by F, and (n) is 1 or 2.  
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